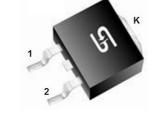
- riigii surge current capability
- Low power loss
- Moisture sensitivity level: level 1, per J-STD-020
- Compliant to RoHS Directive 2011/65/EU and in accordance to WEEE 2002/96/EC
- Halogen-free according to IEC 61249-2-21 definition





TO-263AB (D²PAK)



MECHANICAL DATA

Case: TO-263AB (D²PAK)

Molding compound, UL flammability classification rating 94V-0

Base P/N with suffix "G" on packing code - halogen-free

Base P/N with prefix "H" on packing code - AEC-Q101 qualified **Terminal:** Matte tin plated leads, solderable per JESD22-B102

Meet JESD 201 class 1A whisker test

with prefix "H" on packing code meet JESD 201 class 2 whisker test

Polarity: As marked

Weight: 1.33 g (approximately)

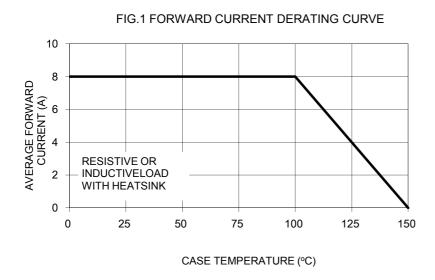
PARAMETER	SYMBOL	SFAS	SFAS	SFAS	SFAS	SFAS	SFAS
PARAIVIE I EK	STIVIBUL	801G	802G	803G	804G	805G	806G
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	150	200	300	400
Maximum RMS voltage	V_{RMS}	35	70	105	140	210	280
Maximum DC blocking voltage	V _{DC}	50	100	150	200	300	400
Maximum average forward rectified current	I _{F(AV)}	8					
Peak forward surge current, 8.3 ms single half sine-wave superimposed on rated load	I _{FSM}	125					
Maximum instantaneous forward voltage _F = 8 A	V _F	0.95 1.3		.3			
Maximum reverse current @ rated V_R T_J =25°C T_J =100°C	I _R	10 400					
Maximum reverse recovery time (Note 1)	t _{rr}	35					
Typical junction capacitance (Note 2)	CJ	80 6					
Typical thermal resistance	$R_{ heta JC}$	2.2					
Operating junction temperature range	T _J	- 55 to +150					
Storage temperature range	T _{STG}	- 55 to +150					

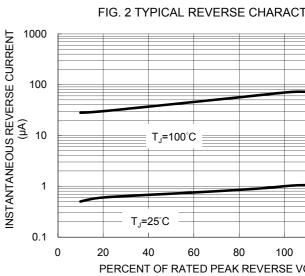
Note 1: Reverse Recovery Test Conditions: I_F =0.5A, I_R =1.0A, I_{RR} =0.25A Note 2: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.

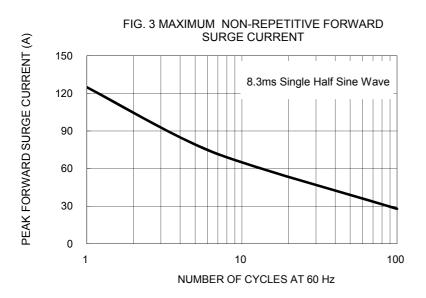
EXAMPLE						
PREFERRED P/N	PART NO.	AEC-Q101 QUALIFIED	PACKING CODE	GREEN COMPOUND CODE	DI	
SFAS801G RN	SFAS801G		RN			
SFAS801G RNG	SFAS801G		RN	G	Gr	
SFAS801GHRN	SFAS801G	Н	RN		AE(

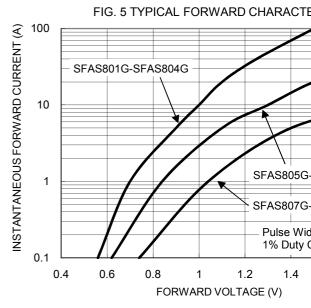
RATINGS AND CHARACTERISTICS CURVES

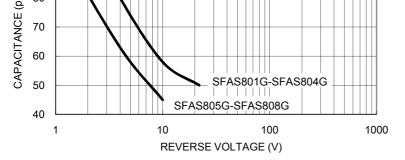
(TA=25°C unless otherwise noted)

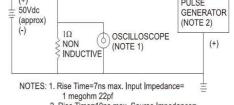








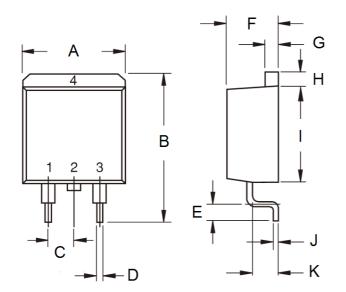






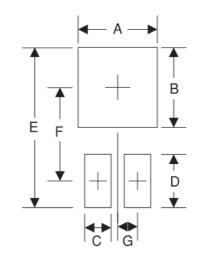
1 megohm 22pf
2. Rise Time=10ns max. Sourse Impedance=

PACKAGE OUTLINE DIMENSIONS



DIM.	Unit	Unit (i		
DIIVI.	Min Max		Min	
Α	-	10.5	-	
В	14.60	15.88	0.575	
С	2.41	2.67	0.095	
D	0.68	0.94	0.027	
Е	2.29	2.79	0.090	
F	4.44	4.70	0.175	
G	1.14	1.40	0.045	
Н	1.14	1.40	0.045	
ı	8.25	9.25	0.325	
J	0.36	0.53	0.014	
K	2.03	2.79	0.080	

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (i				
Α	10.8	0.42				
В	8.3	0.32				
С	1.1	0.04				
D	3.5	0.13				
E	16.9	0.66				
F	9.5	0.37				
G	2.5	0.09				

MARKING DIAGRAM



P/N = Specific Device Code G = Green Compound

YWW = Date Code F = Factory Code

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